# **BUK9M9R5-40H**

# N-channel 40 V, 9.5 mΩ logic level MOSFET in LFPAK33 10 January 2025 Product data sheet

### 1. General description

Automotive qualified logic level N-channel MOSFET in an LFPAK33 package using Trench 9 TrenchMOS technology. This product has been designed and qualified to AEC-Q101 for use in high performance automotive applications.

### 2. Features and benefits

- Fully automotive qualified to AEC-Q101 at 175 °C
- Trench 9 superjunction technology:
  - · Low power losses, high power density
- · LFPAK copper clip package technology:
  - · High robustness and reliability
  - · Gull wing leads for high manufacturability and AOI
- Repetitive avalanche rated

### 3. Applications

- 12 V automotive systems
- · Powertrain, chassis, body and infotainment applications
- · Medium/Low power motor drive
- · DC-DC systems
- LED lighting

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V <sub>DS</sub>	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C		-	-	40	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>	[1]	-	-	40	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	-	55	W
Static characte	eristics						
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ Fig. 11		5.4	7.8	9.5	mΩ
Dynamic chara	ecteristics		•		·		
$Q_{GD}$	gate-drain charge	I <sub>D</sub> = 15 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 4.5 V; Fig. 13; Fig. 14		-	1.7	3.5	nC
Source-drain d	liode		•		·		
Q <sub>r</sub>	recovered charge	$I_S = 15 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V}; V_{DS} = 20 \text{ V}$		-	14	-	nC



Symbol	Parameter	Conditions	Min	Тур	Max	Unit
S		$I_S$ = 15 A; $dI_S/dt$ = -100 A/ $\mu$ s; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V; $T_j$ = 25 °C	-	0.63	-	

<sup>[1] 40</sup>A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

### 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source		D
3	S	source		
4	G	gate		G_(154)
mb	D	Mounting base; connected to drain	1 2 3 4	mbb076 S
			LFPAK33 (SOT1210)	

### 6. Ordering information

### **Table 3. Ordering information**

Type number	Package	<sup>a</sup> ckage					
	Name	Description	Version				
BUK9M9R5-40H	LFPAK33	Plastic, single ended surface mounted package (LFPAK33); 8 leads; 0.65 mm pitch	SOT1210				

### 7. Marking

### Table 4. Marking codes

Type number	Marking code
BUK9M9R5-40H	99н540

# 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Tj = 25 °C unless otherwise stated.

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C		-	40	V
$V_{GS}$	gate-source voltage		[1]	-20	20	V
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	55	W
$I_D$	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>	[2]	-	40	А
		V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 100 °C; <u>Fig. 2</u>		-	38.5	А
I <sub>DM</sub>	peak drain current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 ^{\circ}C$ ; Fig. 3		-	218	А
T <sub>stg</sub>	storage temperature			-55	175	°C
T <sub>j</sub>	junction temperature			-55	175	°C

Symbol	Parameter	Conditions		Min	Max	Unit
Source-drain	n diode					<u>'</u>
Is	source current	T <sub>mb</sub> = 25 °C		-	40	Α
I <sub>SM</sub>	peak source current	pulsed; t <sub>p</sub> ≤ 10 μs; T <sub>mb</sub> = 25 °C		-	218	Α
Avalanche ru	uggedness		'	'	'	
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	$I_D$ = 40 A; $V_{sup} \le 40$ V; $R_{GS}$ = 50 Ω; $V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; unclamped; Fig. 4	[3] [4]	-	19	mJ

- [1] Refer to application note AN90001 for further information.
- [2] 40A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.
- [3] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
- [4] Refer to application note AN10273 for further information.

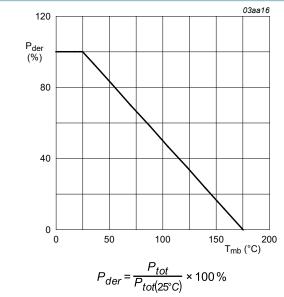
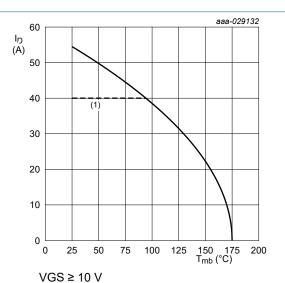
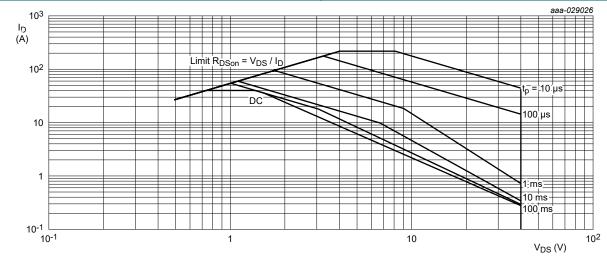


Fig. 1. Normalized total power dissipation as a function of mounting base temperature



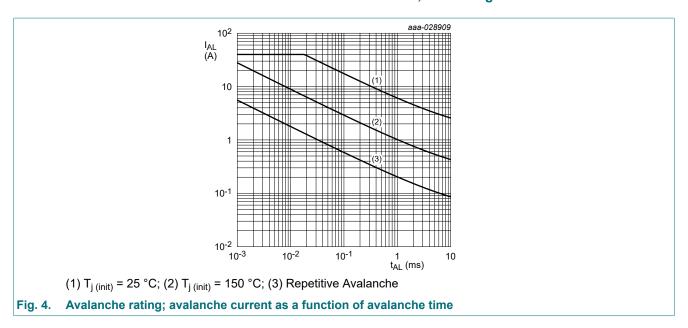
(1) 40A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

Fig. 2. Continuous drain current as a function of mounting base temperature



T<sub>mb</sub> = 25 °C; I<sub>DM</sub> is a single pulse

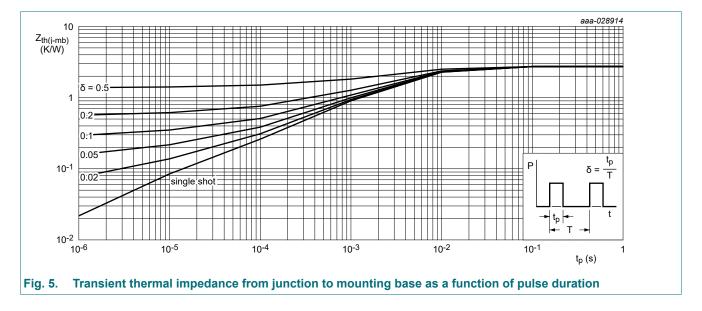
Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage



### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<u>Fig. 5</u>	-	2.51	2.74	K/W



### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics					
V <sub>(BR)DSS</sub>	drain-source	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>i</sub> = 25 °C	40	43	-	V
	breakdown voltage	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>i</sub> = -40 °C	-	40.5	-	V
		I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>i</sub> = -55 °C	36	40	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	I <sub>D</sub> = 1 mA; V <sub>DS</sub> =V <sub>GS</sub> ; T <sub>j</sub> = 25 °C; <u>Fig. 9</u> ; <u>Fig. 10</u>	1.45	1.77	2.15	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C}$	-	-	2.6	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> =V <sub>GS</sub> ; T <sub>j</sub> = 175 °C	0.7	-	-	V
l <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 40 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	0.01	1	μA
		V <sub>DS</sub> = 16 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 125 °C	-	0.37	10	μA
		V <sub>DS</sub> = 40 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 175 °C	-	31	500	μA
l <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 16 V; V <sub>DS</sub> = 0 V; T <sub>i</sub> = 25 °C	-	2	100	nA
		V <sub>GS</sub> = -16 V; V <sub>DS</sub> = 0 V; T <sub>i</sub> = 25 °C	-	2	100	nA
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = 10 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 25 °C; Fig. 11	5.4	7.8	9.5	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 105 °C; Fig. 12	7.4	11.3	14.3	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 125 °C; Fig. 12	8.1	12.3	15.3	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 175 °C; Fig. 12	9.8	14.8	18.4	mΩ
		$V_{GS}$ = 4.5 V; $I_{D}$ = 10 A; $T_{j}$ = 25 °C; Fig. 11	6.7	9.6	12	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 10 A; T <sub>j</sub> = 105 °C; Fig. 12	9.1	13.7	18	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 10 A; T <sub>j</sub> = 125 °C; Fig. 12	10.1	14.8	19.3	mΩ
		$V_{GS}$ = 4.5 V; $I_{D}$ = 10 A; $T_{j}$ = 175 °C; Fig. 12	12.2	17.8	23.3	mΩ
$R_G$	gate resistance	f = 1 MHz; T <sub>j</sub> = 25 °C	0.3	0.9	2.3	Ω
Dynamic ch	naracteristics		·	·	·	
$Q_{G(tot)}$	total gate charge	I <sub>D</sub> = 15 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 10 V; Fig. 13; Fig. 14	-	17	24	nC
		$I_D = 15 \text{ A}; V_{DS} = 20 \text{ V}; V_{GS} = 4.5 \text{ V};$	-	8	11	nC
Q <sub>GS</sub>	gate-source charge	Fig. 13; Fig. 14	-	3	4.5	nC
$Q_{GD}$	gate-drain charge		-	1.7	3.5	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0 V; f = 1 MHz;	-	1098	1537	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; <u>Fig. 15</u>	-	342	479	pF
C <sub>rss</sub>	reverse transfer capacitance		-	41	90	pF
d(on)	turn-on delay time	$V_{DS} = 20 \text{ V}; R_L = 1.2 \Omega; V_{GS} = 4.5 \text{ V};$	-	8.6	-	ns
r	rise time	$R_{G(ext)} = 5 \Omega$	-	8.1	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	10.5	-	ns
t <sub>f</sub>	fall time	1	-	5.2	-	ns

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Source-drain diode						•	<u>'</u>
V <sub>SD</sub>	source-drain voltage	$I_S = 15 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}; Fig. 16$		-	0.85	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = 15 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$		-	21	-	ns
Q <sub>r</sub>	recovered charge	V <sub>DS</sub> = 20 V		-	14	-	nC
S	softness factor	$I_S$ = 15 A; $dI_S/dt$ = -100 A/ $\mu$ s; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V; $T_j$ = 25 °C		-	0.63	-	
		$I_S$ = 15 A; $dI_S/dt$ = -500 A/ $\mu$ s; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V; $T_j$ = 25 °C		-	0.43	-	

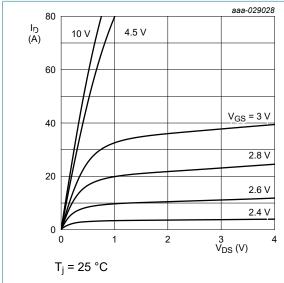


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

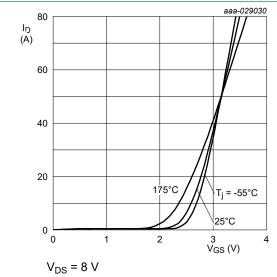


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values

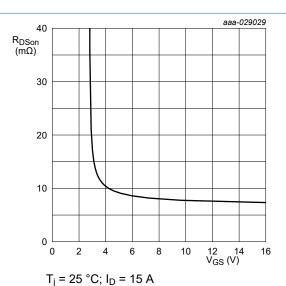


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

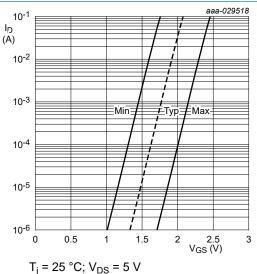


Fig. 9. Sub-threshold drain current as a function of gate-source voltage

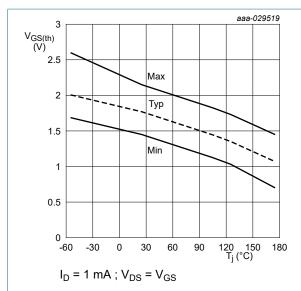


Fig. 10. Gate-source threshold voltage as a function of junction temperature

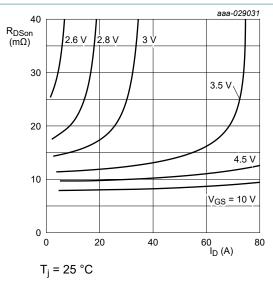


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

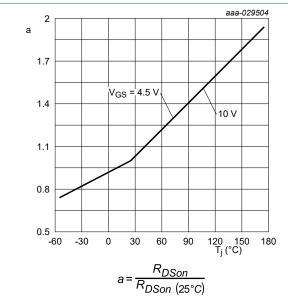


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

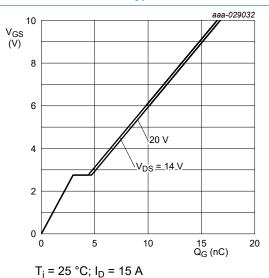


Fig. 13. Gate-source voltage as a function of gate charge; typical values

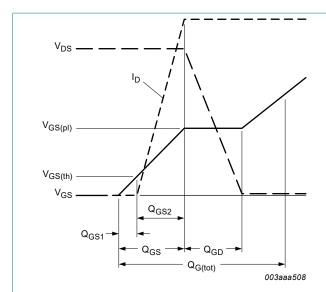
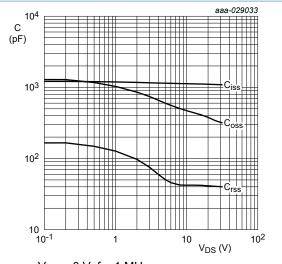


Fig. 14. Gate charge waveform definitions



 $V_{GS} = 0 V$ ; f = 1 MHz

Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

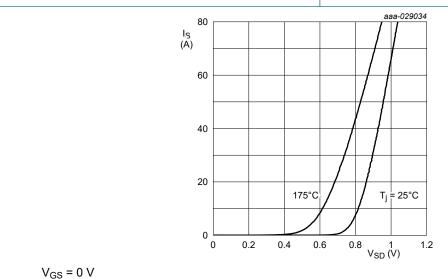
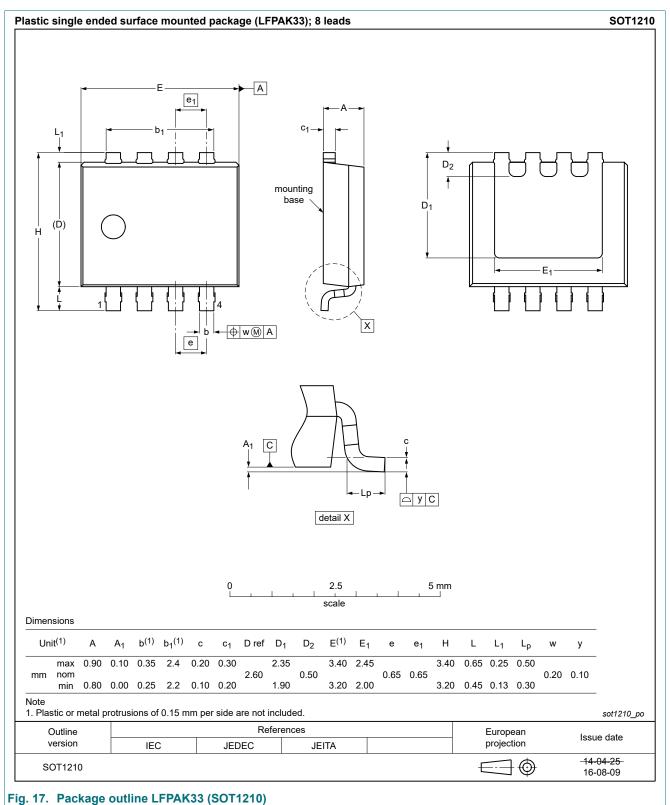


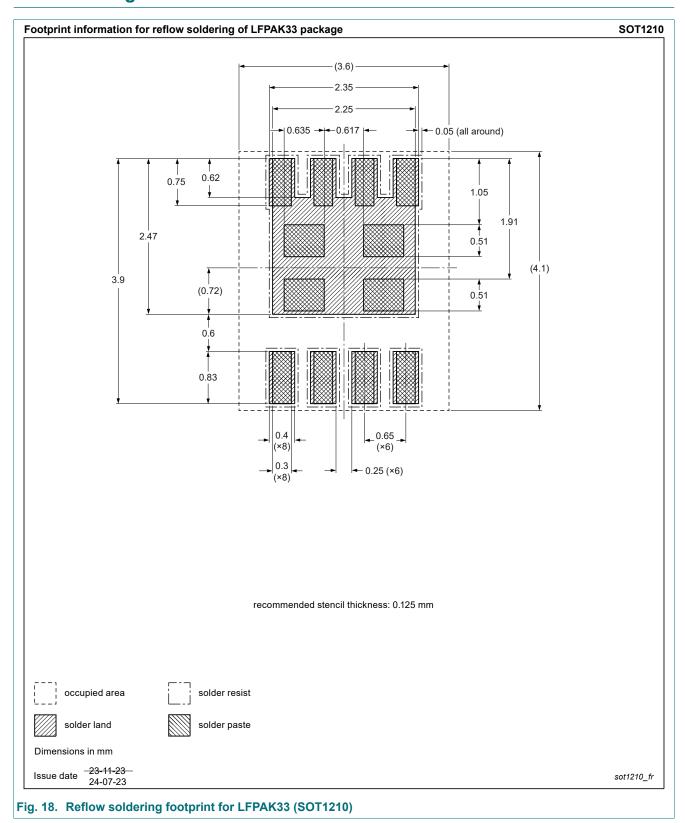
Fig. 16. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values

### 11. Package outline



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### 12. Soldering



### 13. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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